	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L7	2544	simulat$3 same wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 12:53
2	BRS	L8	130	7 same (photoresist same metal or aluminum or copper or tungsten)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:10
3	BRS	L9	43	8 and @pd<19990331	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:10
4	BRS	L10	13	7 same (photoresist same (metal or aluminum or copper or tungsten))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:48
5	BRS	L11	9	10 and @pd<19990331	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:25
6	BRS	L12	139	simulat$3 same (test near wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:25
7	BRS	L13	36	12 and @pd<19990331	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:49
8	BRS	L14	3	13 and (photoresist same pattern$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:34

	Type	L #	Hits	Search Text	DBs	Time Stamp
9	BRS	L15	12209	((photoresist or resin$3 or polymer$3) same (metal or copper or aluminum)) same wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:36
10	BRS	L16	19	((photoresist or resin$3 or polymer$3) same (metal or copper or aluminum)) same (wafer same simulat$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:36
11	BRS	L17	2125	mixture same (photoresist same (metal or aluminum or copper or tungsten))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:49
12	BRS	L18	182	17 and ((test$3 or simulat$3) same wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:49
13	BRS	L19	95	18 and @pd<19990331	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:50
14	BRS	L20	94	19 and etch$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:51
15	BRS	L23	0	goldspring-gregory.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 14:20
16	BRS	L24	6	goldspring-gregory-j.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 14:20